

TECHNIQUES FOR CREATING OPTIMIZED PAD GEOMETRIES FOR SOLDERING

ABSTRACT OF THE DISCLOSURE

5 A technique for processing a circuit board involves placing a mask layer on the circuit board, where the mask layer defines a set of pad profiles for a component mounting location. Each pad profile has a set of rounded corners. The technique further involves forming, for each pad profile, a soldering pad having a set of radii corresponding to the set of rounded corners of that pad profile to create a set of
10 soldering pads for the component mounting location. Each soldering pad is configured for a high bond strength solder joint. The technique further involves removing the mask layer from the circuit board and soldering a component to the component mounting location. This technique is well-suited for robustly mounting the component to the circuit board at solder joints with relatively high solder joint bond strengths.

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